

# HSF

Recommended P.C.B Layout(Top Side)  
(PCB BOARD TOLERANCE±0.05)

NOTES:  
 Current Rating:1.0AMP  
 Contact Resistance:20mΩ Max  
 Withstand Voltage:500V AC/DC  
 Insulation Resistance:1000MΩ Min  
 Operation Temperature:-40°C to +105°C

Contact Material:Phosphor Bronze  
 Contact plating:Au over Ni  
 Insulator Material:PA9T+30%GF UL94V-0

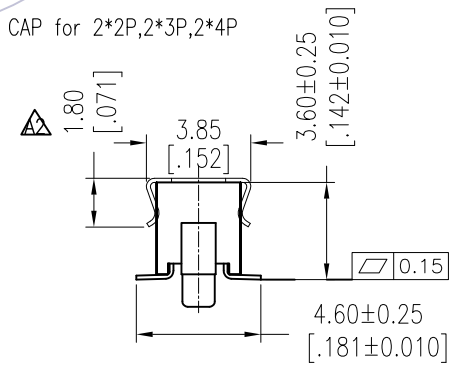
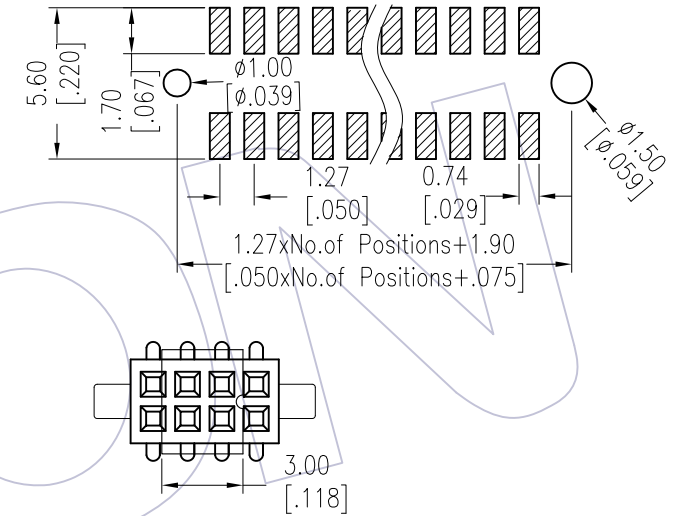
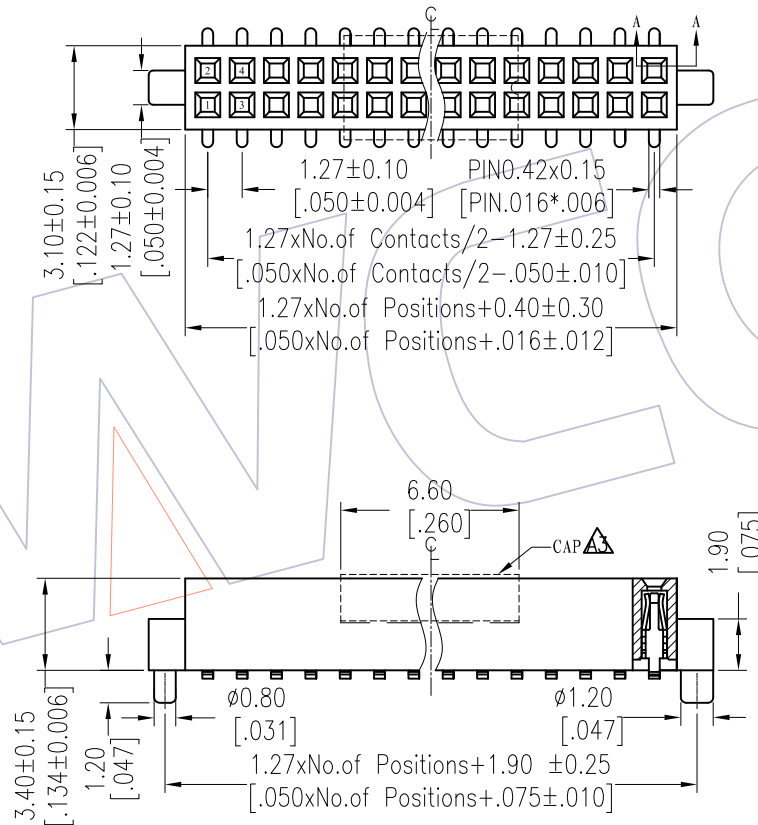
## Ordering Information

2334-2 XX M XX CUN X 3

No. of Pins per Row: 02-50Pin

Contact Plating:  
 G0=Gold Flash  
 G3=10u"Gold  
 G4=15u"Gold  
 G5=30u"Gold

Packing:  
 T=Tube  
 P=Tube+CAP  
 R=Tape&Reel+CAP



Item	Pitch	Mating
Standard	1.27	1310/1315/1320/3131
Alternate		

REV	DATE	MODIFICATION DESCRIPTION	CHANGE	DIM	TOL	OPERATION	DRAW	DATE	SCALE	FIT	PART NO.	TITLE:
A3	2014/12/30	Modify CAP	-----			OPERATION	wang	2014/12/30	UNIT	mm	2334-2XXMXXCUNX3	
A2	2013/08/21	Modify cap 2.00 → 1.80	-----	x.X	±0.40		CHECK		SIZE	A4		FH1.27mm DUAL ROW 180° SMT WITH DIFFERENT POST AND METAL CAP H=3.40
A1	2013/07/01	Modify drawing	-----	x.XX	±0.25		APPROVE		SHEET	1/1		
A0	2012/07/06	NEW	-----	x.XXX	±0.15				PROJ.	Customer NO.		